



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD218-B1-02EL E6327		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001220734						
<b>Package</b>		PG-TSLP-2-20		<b>Weight*</b>		0.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.11		1134	
	noble metal	gold	7440-57-5	0.003	0.44		4401	
	inorganic material	silicon	7440-21-3	0.033	5.37	5.92	53704	59239
leadframe	non noble metal	nickel	7440-02-0	0.241	39.14	39.14	391370	391370
wire	noble metal	gold	7440-57-5	0.006	0.91	0.91	9055	9055
	encapsulation	organic material	carbon black	1333-86-4	0.002	0.25		2505
	plastics	epoxy resin	-	0.045	7.27		72670	
		inorganic material	silicondioxide	60676-86-0	0.262	42.60	50.12	425996
leadfinish	noble metal	gold	7440-57-5	0.010	1.69	1.69	16947	16947
plating	noble metal	palladium	7440-05-3	0.003	0.53		5271	
		noble metal	gold	7440-57-5	0.010	1.69	2.22	16947
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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